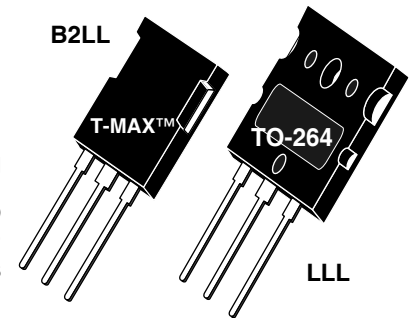
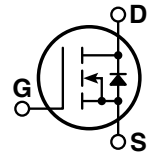




Power MOS 7[®] is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7[®] by significantly lowering $R_{DS(ON)}$ and Q_g . Power MOS 7[®] combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with Microsemi's patented metal gate structure.



- Lower Input Capacitance
- Lower Miller Capacitance
- Lower Gate Charge, Q_g
- Increased Power Dissipation
- Easier To Drive
- Popular T-MAX[™] or TO-264 Package


MAXIMUM RATINGS

 All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APT6010B2_LLL	UNIT
V_{DSS}	Drain-Source Voltage	600	Volts
I_D	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	54	Amps
I_{DM}	Pulsed Drain Current ^①	216	
V_{GS}	Gate-Source Voltage Continuous	± 30	Volts
V_{GSM}	Gate-Source Voltage Transient	± 40	
P_D	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	690	Watts
	Linear Derating Factor	5.52	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I_{AR}	Avalanche Current ^① (Repetitive and Non-Repetitive)	54	Amps
E_{AR}	Repetitive Avalanche Energy ^①	50	mJ
E_{AS}	Single Pulse Avalanche Energy ^④	3000	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage ($V_{GS} = 0V, I_D = 250\mu\text{A}$)	600			Volts
$R_{DS(on)}$	Drain-Source On-State Resistance ^② ($V_{GS} = 10V, I_D = 27A$)			0.100	Ohms
I_{DSS}	Zero Gate Voltage Drain Current ($V_{DS} = 600V, V_{GS} = 0V$)			100	μA
	Zero Gate Voltage Drain Current ($V_{DS} = 480V, V_{GS} = 0V, T_C = 125^\circ\text{C}$)			500	
I_{GSS}	Gate-Source Leakage Current ($V_{GS} = \pm 30V, V_{DS} = 0V$)			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage ($V_{DS} = V_{GS}, I_D = 2.5mA$)	3		5	Volts

 **CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Microsemi Website - <http://www.microsemi.com>

DYNAMIC CHARACTERISTICS

APT6010B2_LLL

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{iss}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{ MHz}$		6710		pF
C_{oss}	Output Capacitance			1250		
C_{riss}	Reverse Transfer Capacitance			90		
Q_g	Total Gate Charge ③	$V_{GS} = 10V$ $V_{DD} = 300V$ $I_D = 54A @ 25^\circ C$		150		nC
Q_{gs}	Gate-Source Charge			30		
Q_{gd}	Gate-Drain ("Miller") Charge			75		
$t_{d(on)}$	Turn-on Delay Time	RESISTIVE SWITCHING $V_{GS} = 15V$ $V_{DD} = 300V$ $I_D = 54A @ 25^\circ C$ $R_G = 0.6\Omega$		12		ns
t_r	Rise Time			19		
$t_{d(off)}$	Turn-off Delay Time			34		
t_f	Fall Time			9		
E_{on}	Turn-on Switching Energy ⑥	INDUCTIVE SWITCHING @ 25^\circ C $V_{DD} = 400V, V_{GS} = 15V$ $I_D = 54A, R_G = 5\Omega$		885		μJ
E_{off}	Turn-off Switching Energy			970		
E_{on}	Turn-on Switching Energy ⑥	INDUCTIVE SWITCHING @ 125^\circ C $V_{DD} = 400V, V_{GS} = 15V$ $I_D = 54A, R_G = 5\Omega$		1150		
E_{off}	Turn-off Switching Energy			1220		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I_S	Continuous Source Current (Body Diode)			54	Amps
I_{SM}	Pulsed Source Current ① (Body Diode)			216	
V_{SD}	Diode Forward Voltage ② ($V_{GS} = 0V, I_S = -54A$)			1.3	Volts
t_{rr}	Reverse Recovery Time ($I_S = -54A, di_S/dt = 100A/\mu s$)		790		ns
Q_{rr}	Reverse Recovery Charge ($I_S = -54A, di_S/dt = 100A/\mu s$)		18		μC
dv/dt	Peak Diode Recovery dv/dt ⑤			8	V/ns

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.18	$^\circ C/W$
$R_{\theta JA}$	Junction to Ambient			40	

- ① Repetitive Rating: Pulse width limited by maximum junction temperature
 - ② Pulse Test: Pulse width < 380 μs , Duty Cycle < 2%
 - ③ See MIL-STD-750 Method 3471
 - ④ Starting $T_J = +25^\circ C, L = 2.06mH, R_G = 25\Omega, \text{Peak } I_L = 54A$
 - ⑤ dv/dt numbers reflect the limitations of the test circuit rather than the device itself. $I_S \leq -I_D 54A, di/dt \leq 700A/\mu s, v_R \leq 600V, T_J \leq 150^\circ C$
 - ⑥ Eon includes diode reverse recovery. See figures 18, 20.
- Microsemi reserves the right to change, without notice, the specifications and information contained herein.

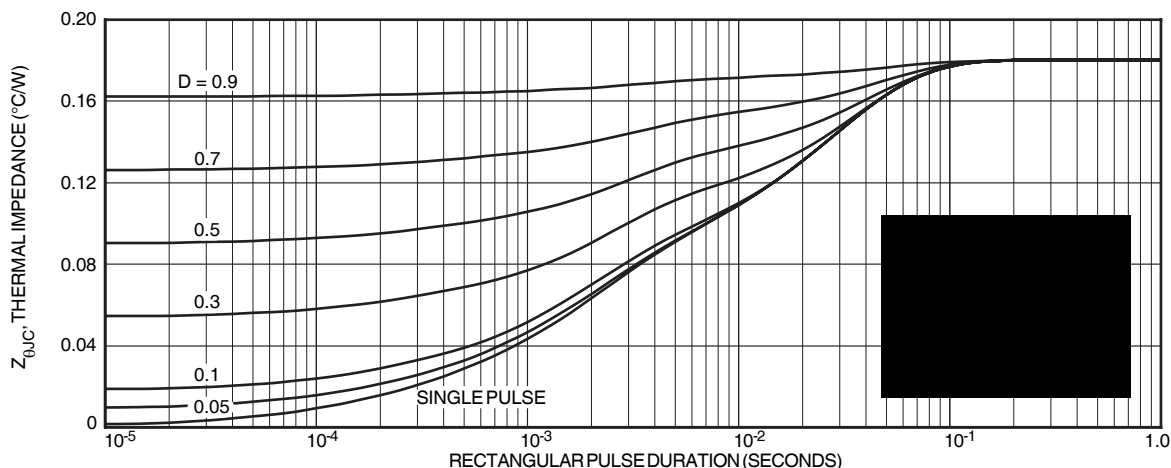


FIGURE 1, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION

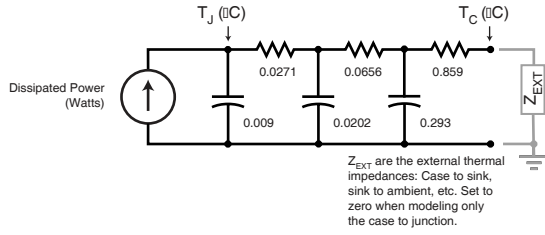


FIGURE 2, TRANSIENT THERMAL IMPEDANCE MODEL

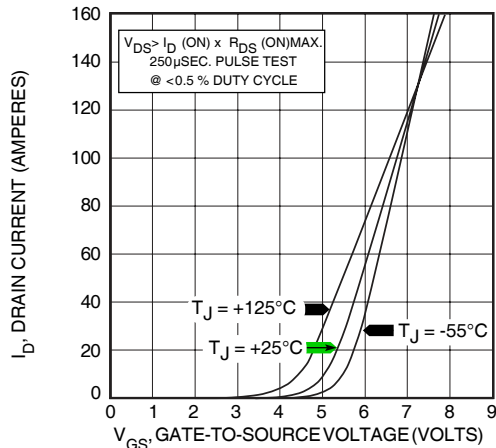


FIGURE 4, TRANSFER CHARACTERISTICS

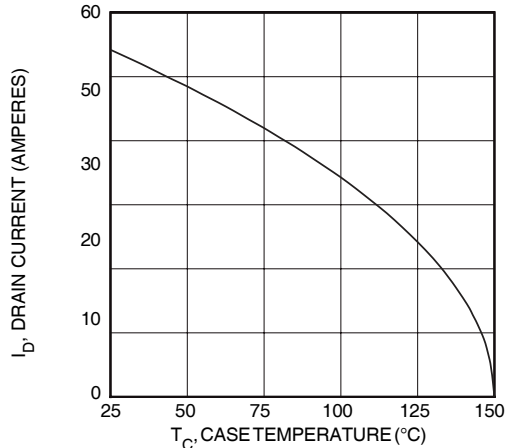


FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE

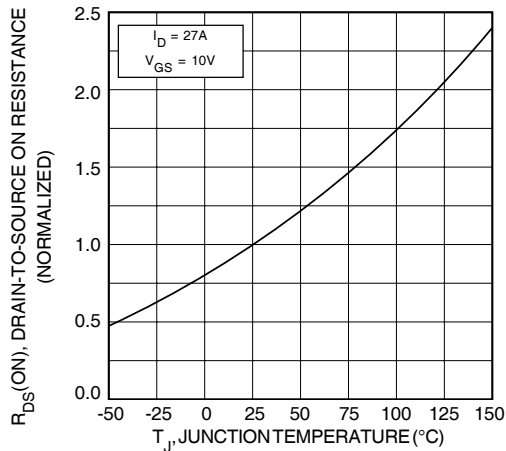


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

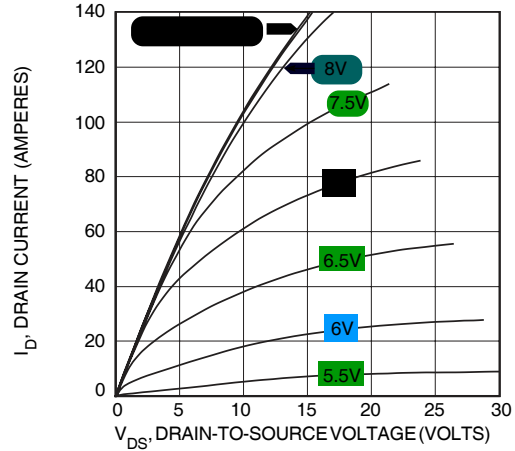


FIGURE 3, LOW VOLTAGE OUTPUT CHARACTERISTICS

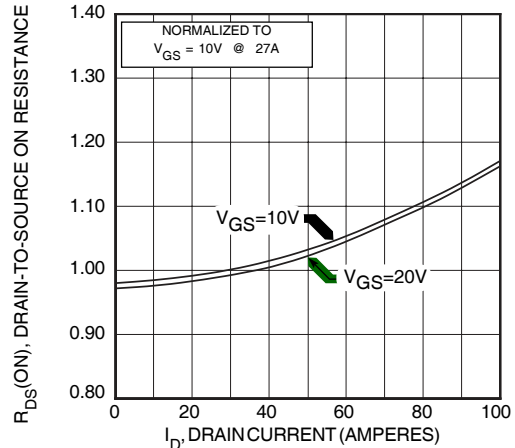


FIGURE 5, $R_{DS(ON)}$ vs DRAIN CURRENT

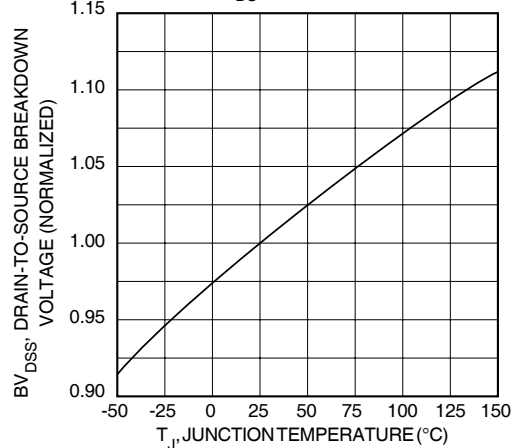


FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE

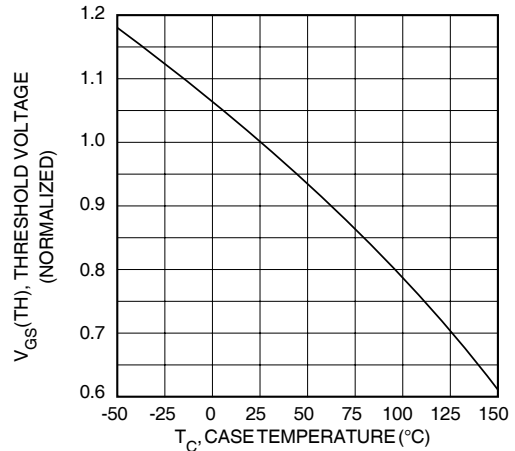


FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE

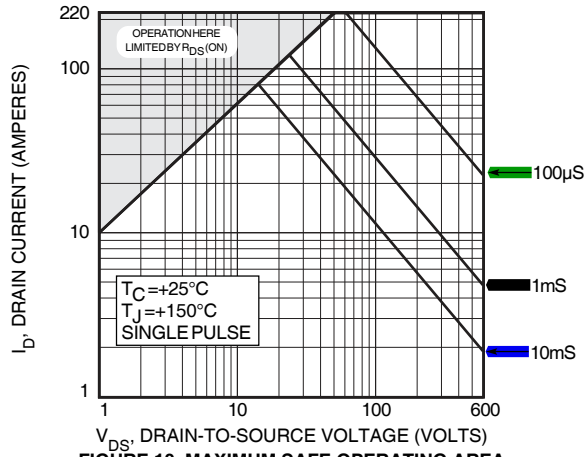


FIGURE 10, MAXIMUM SAFE OPERATING AREA

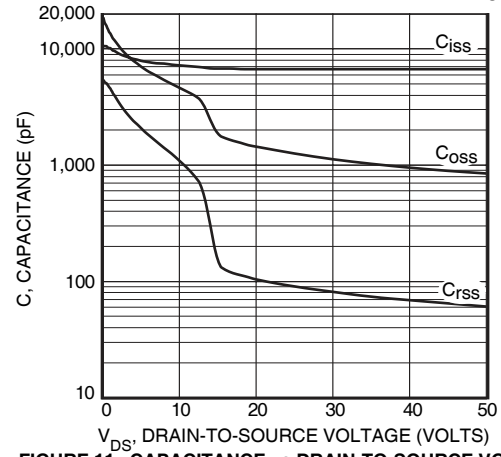


FIGURE 11, CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

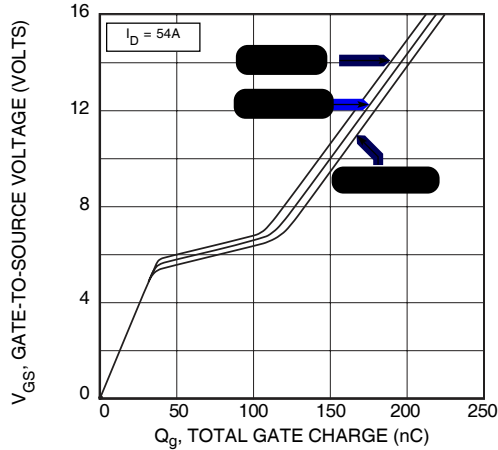


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

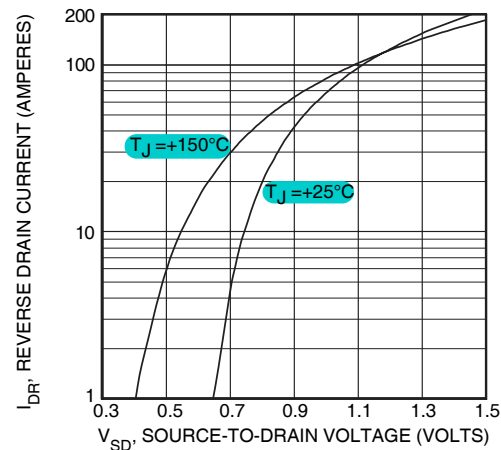


FIGURE 13, SOURCE-DRAIN DIODE FORWARD VOLTAGE

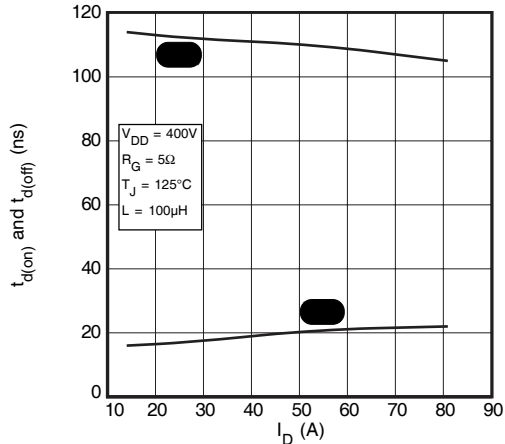


FIGURE 14, DELAY TIMES vs CURRENT

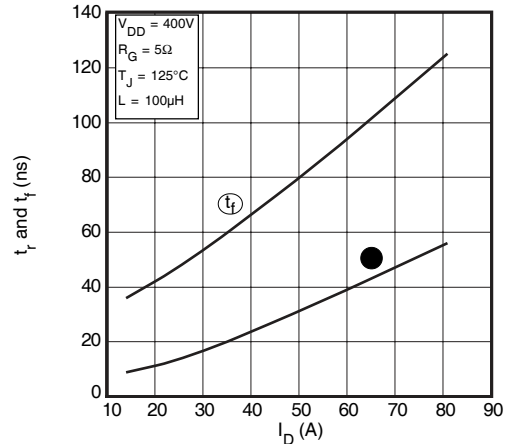


FIGURE 15, RISE AND FALL TIMES vs CURRENT

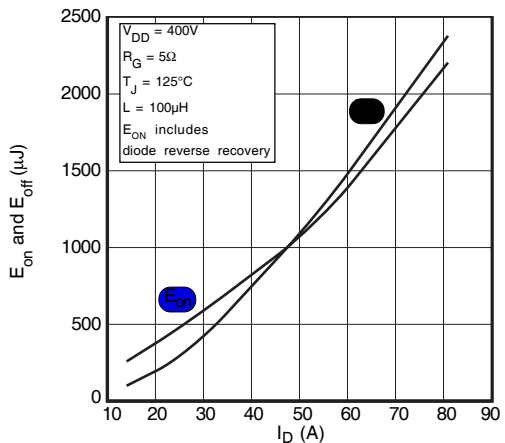


FIGURE 16, SWITCHING ENERGY vs CURRENT

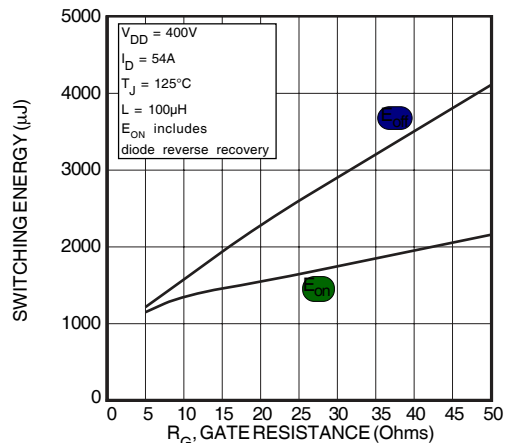


FIGURE 17, SWITCHING ENERGY vs. GATE RESISTANCE

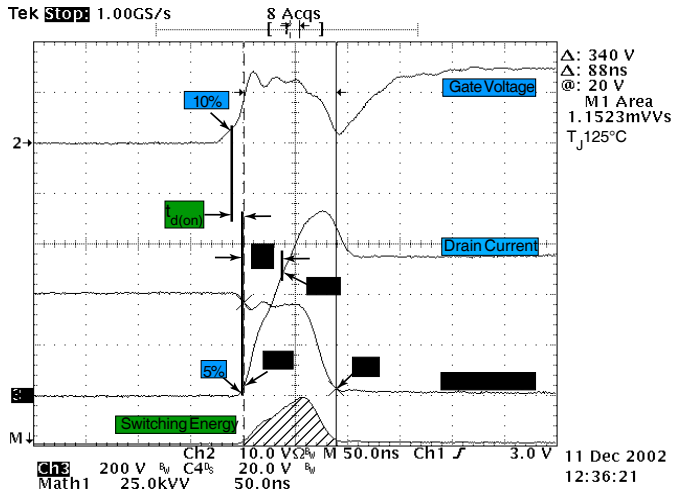


Figure 18, Turn-on Switching Waveforms and Definitions

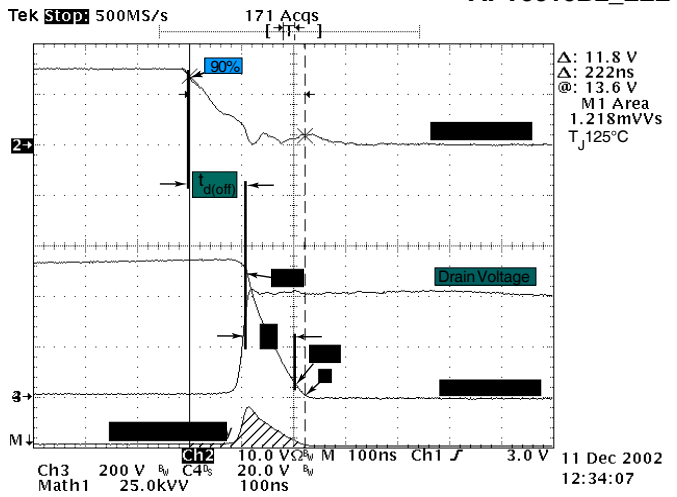


Figure 19, Turn-off Switching Waveforms and Definitions

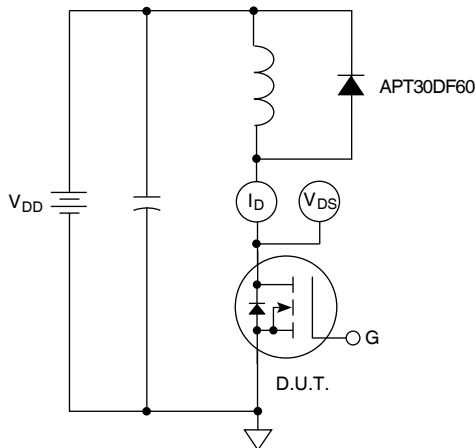
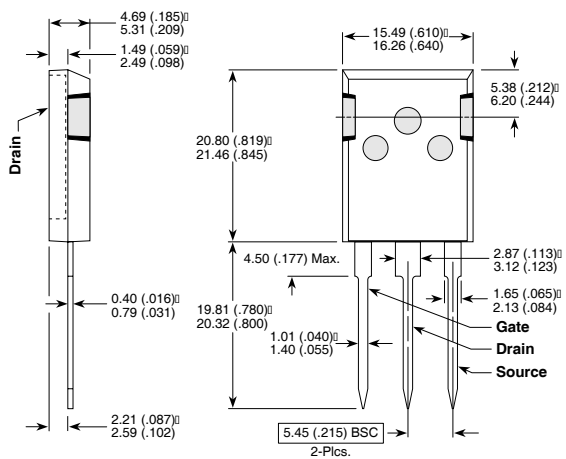


Figure 20, Inductive Switching Test Circuit

T-MAX™ (B2) Package Outline

(e1) SAC: Tin, Silver, Copper

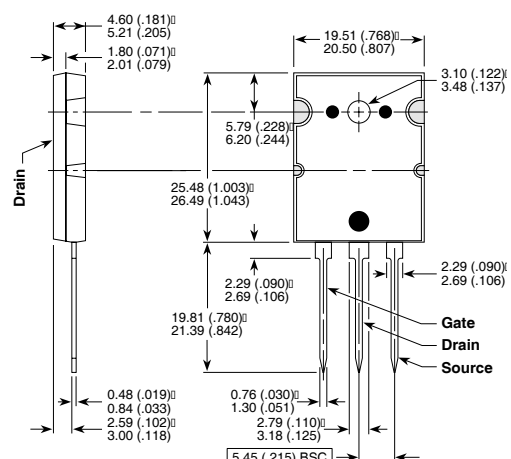


These dimensions are equal to the TO-247 without the mounting hole.

Dimensions in Millimeters and (Inches)

TO-264 (L) Package Outline

(e1) SAC: Tin, Silver, Copper



Dimensions in Millimeters and (Inches)